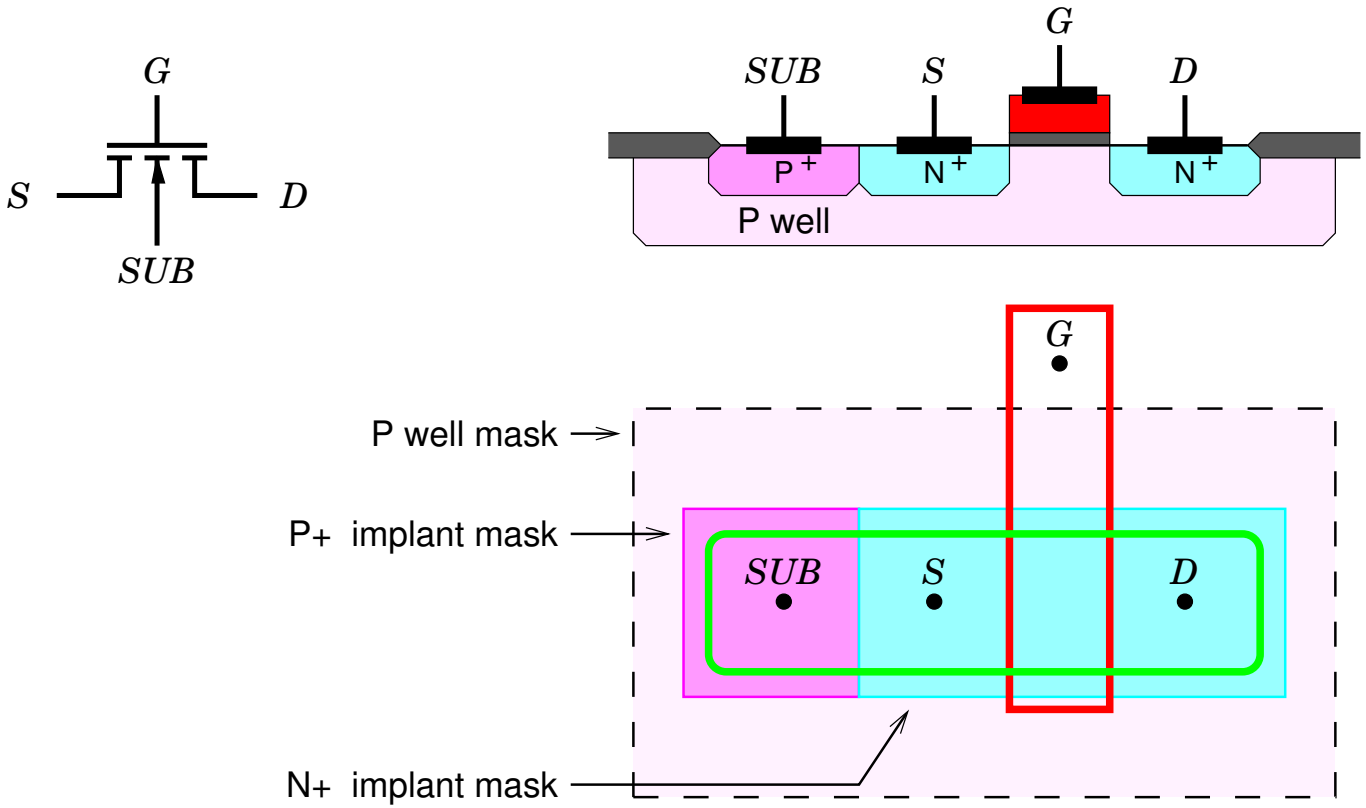
NMOS Transistor – with top substrate connection

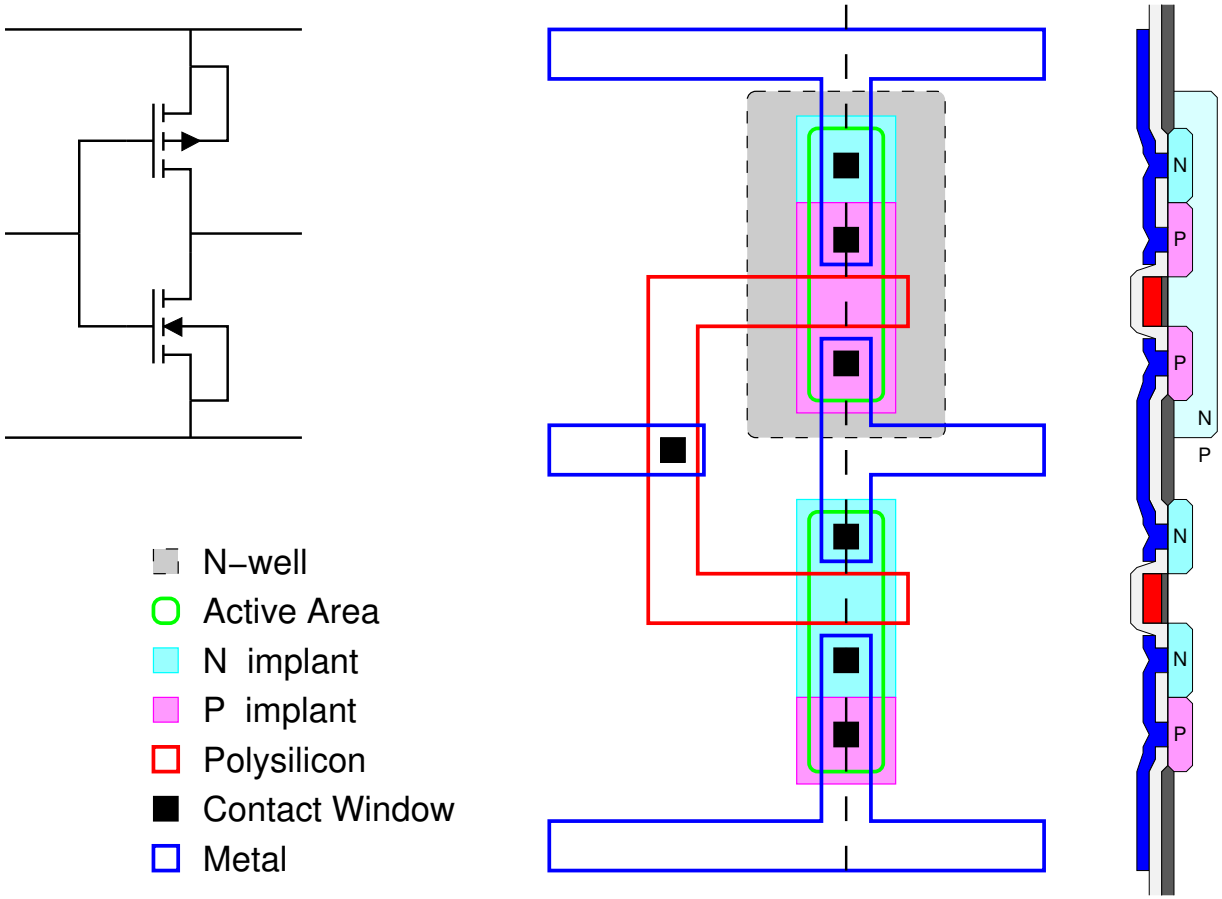


NMOS Transistor – with top substrate connection

Where it is not suitable for substrate connections to be shared, a more complex process is used.

- Five masks must be used to define the transistor:
  - P Well
  - Active Area
  - Polysilicon
  - N+ implant
  - P+ implant
- P Well, for isolation.
- Top *substrate* connection.
- P+/N+ implants produce good *ohmic* contacts.

CMOS Inverter



CMOS Inverter

- The process described here is an *N Well process* since it has only an N Well.

  P Well and Twin Tub processes also exist.

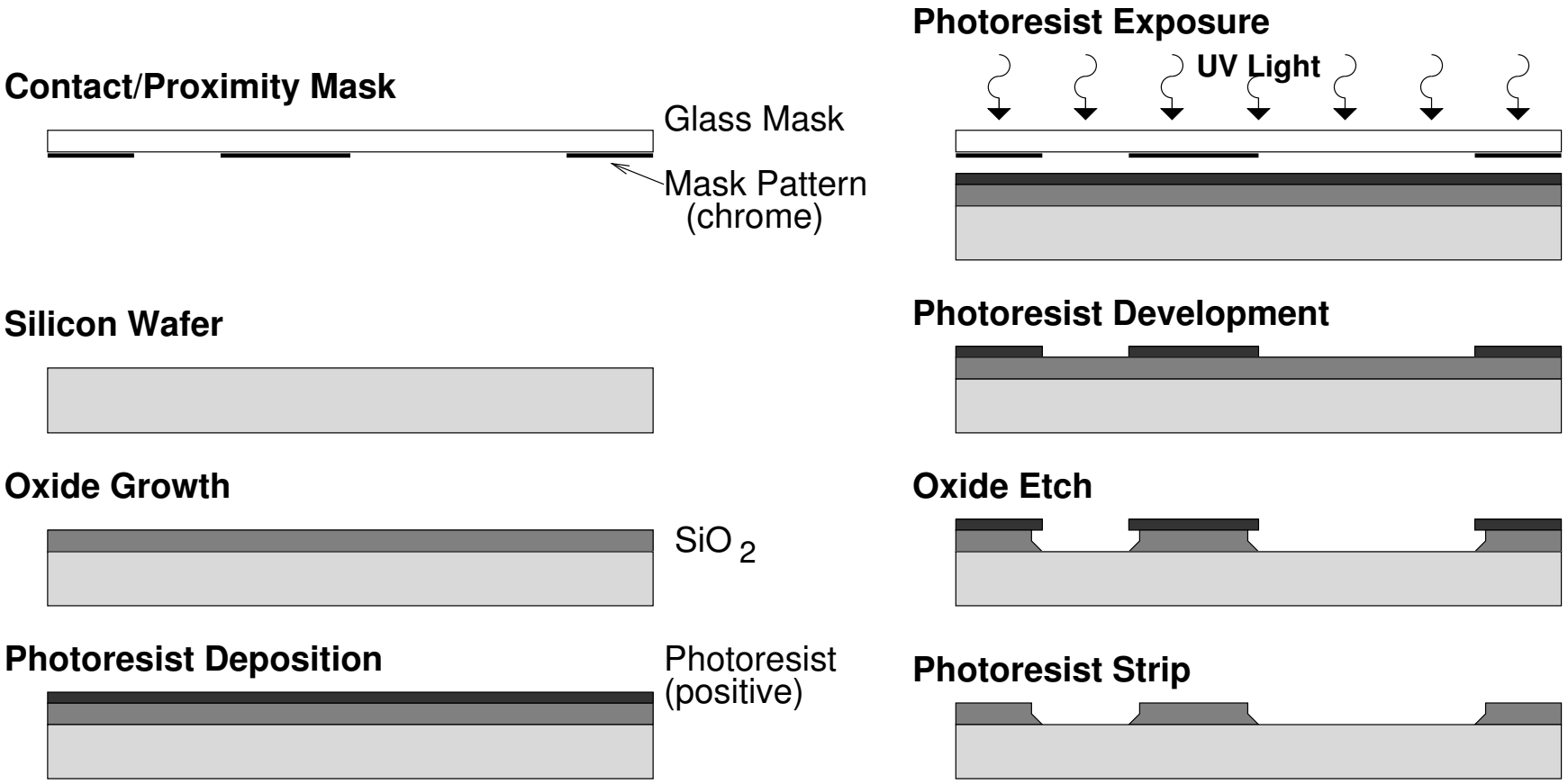
- Note that the P-N junction between chip substrate and N Well will remain reverse biased.

  Thus the transistors remain isolated.

- N implant defines NMOS source/drain and PMOS substrate contact.

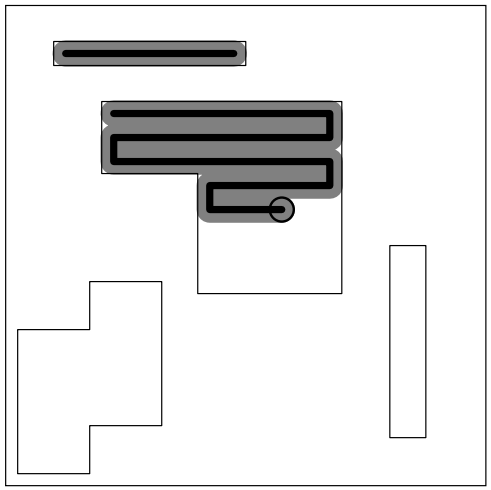
- P implant defines PMOS source/drain and NMOS substrate contact.

Processing – Photolithography

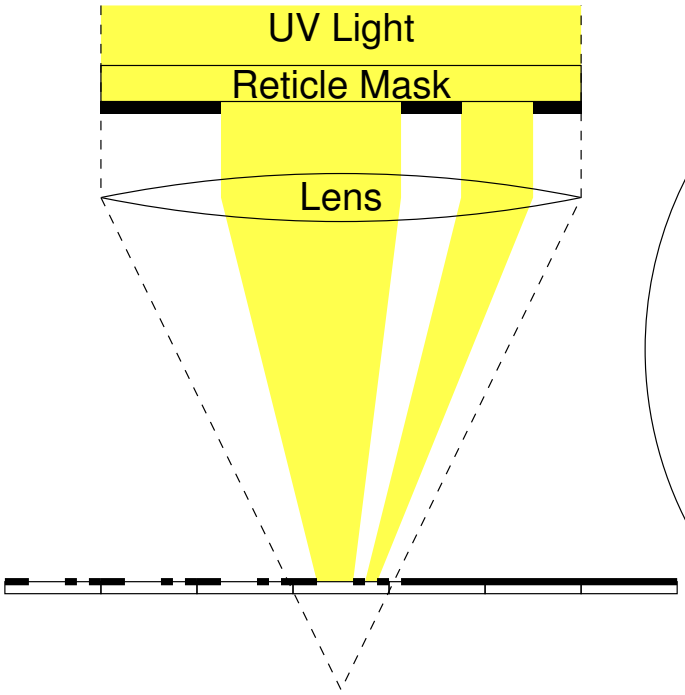


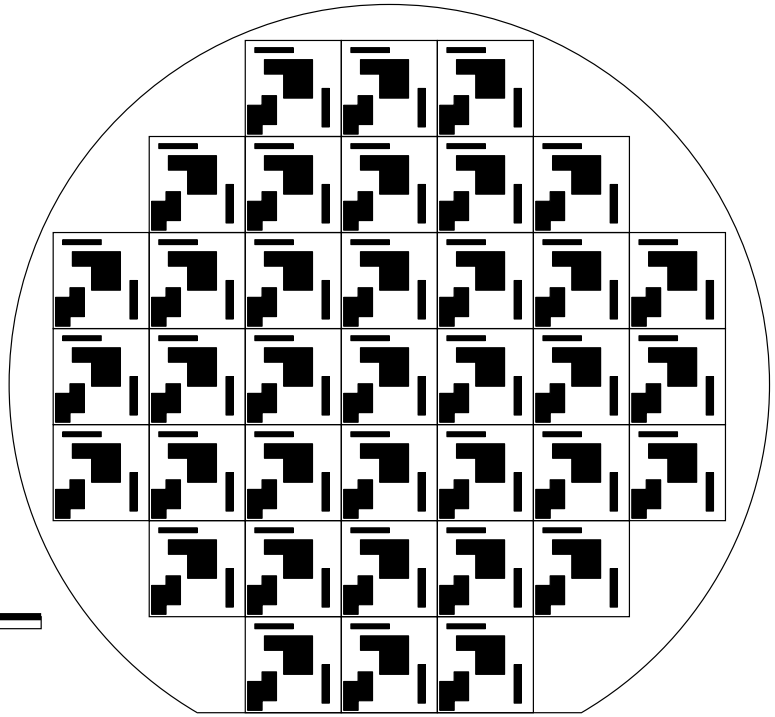
Processing – Mask Making

Reticle written by scanning electron beam

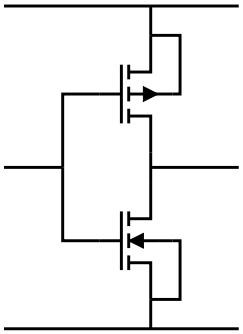


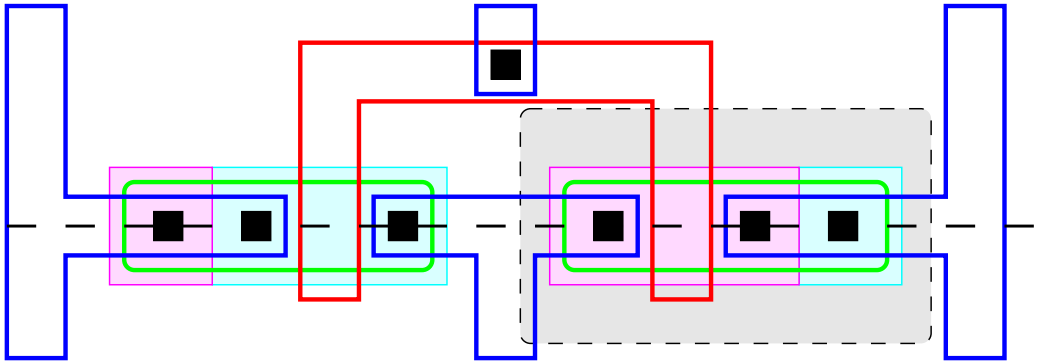
Pattern reproduced on wafer (or contact/proximity mask) by step and repeat with optical reduction





- Optical reduction allows narrower line widths.





N–well

Active Area
defines Thick Oxide

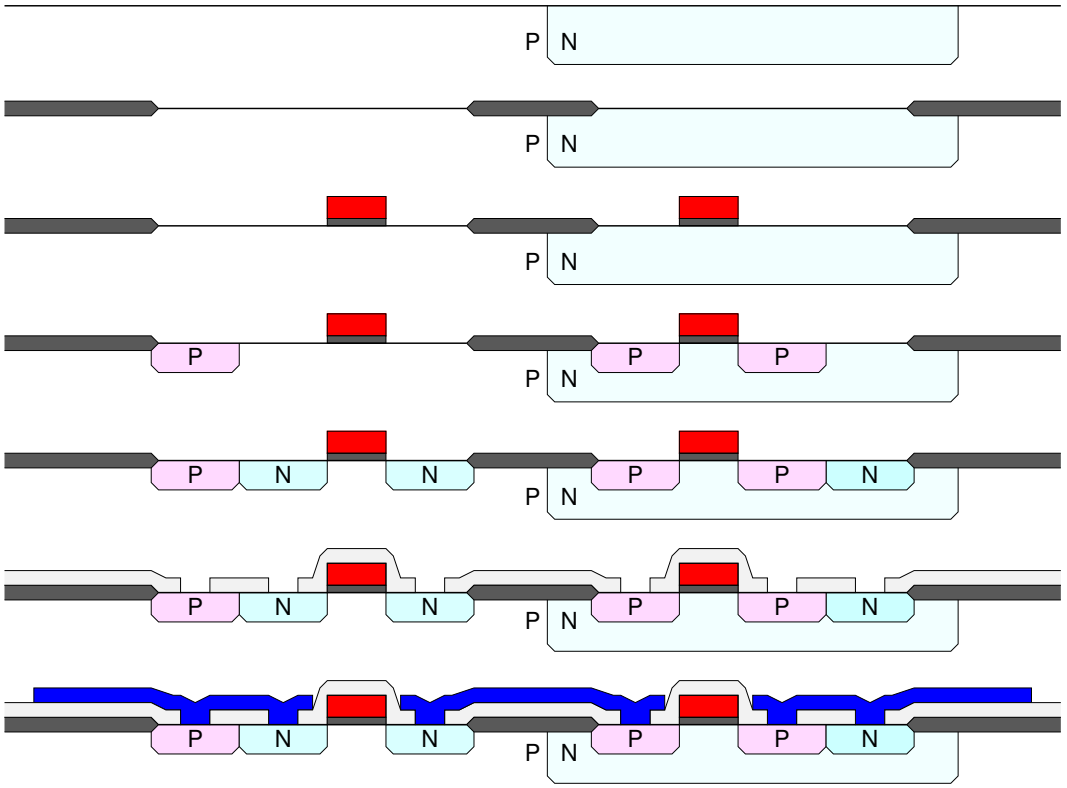
Polysilicon
defines Thin Oxide

P implant
aligned to AA and Poly

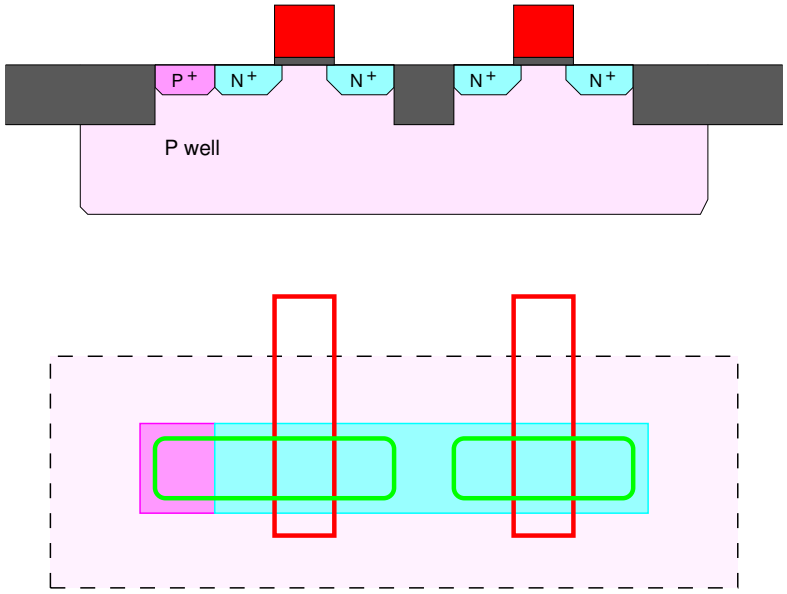
N implant
aligned to AA and Poly

Contact Window

Metal



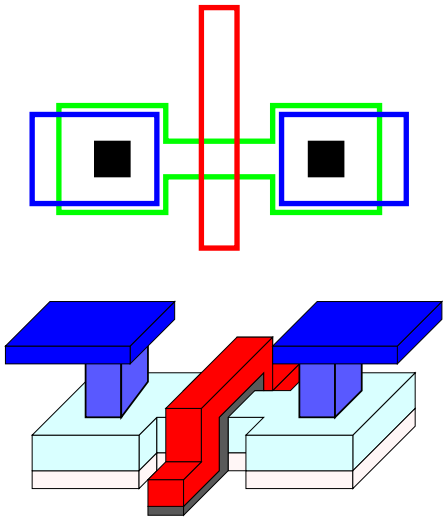
Shallow Trench Isolation



- Rather than grow the thick oxide, dig[1] a trench and deposit silicon oxide in the space.
- Deeper oxide, sharper edges, better isolation.

[1] etch away

Fin FET



- With the aid of trenches we raise the active area above the bulk silicon.
- We can then wrap the gate around the channel.
- Avoids an effect where a channel is created in a region which is closer to the drain than the gate.